ABSTRACT

SYSTEMS FOR DEGATING PACKAGED SEMICONDUCTOR DEVICES WITH TAPE SUBSTRATES

A system for degating a packaged semiconductor device that includes a tape substrate includes a first element and a second element. The first element of the system is positionable adjacent to a first major surface of the packaged semiconductor device and includes a receptacle for receiving a portion of a gate of the packaged semiconductor device. A second element of the degating system is positionable adjacent to a second major surface of the packaged semiconductor device and includes a degating element alignable with the gate. The degating element is extendable through the gate to force a portion of the gate and a sprue therein into the receptacle of the first element.

[FIG. 24]